



震讯科技

ZHENXUN TECHNOLOGY

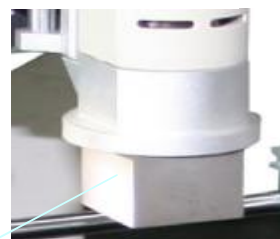
ZX-C1三温区BGA返修站

红外发热区
IR heater



上部风扇调节按钮
Adjust button of top fan

上部加热头
Top heater



下部加热头
Bottom heater

销售热线: 186 6538 6516王振超

上部加热头
Top heater



采用德国进口发热管热风加热，为BGA上部作主要加热；内部集合吸嘴设计，在对位和拆卸时手动控制。

Top heater use hot air to heat the top side of BGA, heating tube is made in Germany. Pick, place, welding, reflow auto.

下部加热头
Bottom heater



采用德国进口发热管热风加热，为BGA下部的PCB板作辅助加热；在喷嘴上方可安装支撑架，支撑PCB，防止PCB局部变形。

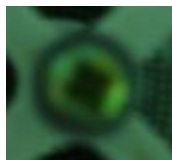
Bottom heater use hot air to heat the bottom side of BGA, heating tube is made in Germany. There is support on top of nozzle to prevent PCB deformation

红外发热区
IR heater



采用红外（IR）加热，为整体PCB进行预热，防止PCB温差过大变形；上方可加支撑条，采用多点支撑，防止大面积变形。

Use IR heater to preheat the whole PCB board to avoid temperature difference cause deformation. There is support on top of IR heater to prevent PCB deformation



发热芯

heater

销售热线：186 6538 6516王振超



震讯科技

ZHENXUN TECHNOLOGY

特点:

1. 手动操作，仪表控温，按钮控制。手动调节上部加热器高度，拆卸时用吸笔手动吸起BGA元件。
2. 一、二温区加热器采用热风控制，三温区预热采用IR红外控制（不可见光，暗红外）；
一温区（上部加热器）与吸嘴一体化设计；
二温区（下部加热器）可上下调节，支撑BGA下部的局部PCB板下沉；
3. 一温区(上部风头)以8段升（降）温+8段恒温控制；可存储10组温度曲线参数；二温区（下部风头）、三温区（红外发热区）1段升温+1段恒温控制；
4. 三个加热区采用独立的PID算法控制加热过程，升温更均匀，温度更准确；
5. 下部热风加热区配有组合型支撑架，可微调支撑BGA下部PCB板，限制焊接区局部下沉；
6. 下部IR预热区采用大型多点可调支撑柱，防止PCB板大面积下沉；
7. 在拆卸、焊接完毕后采用恒流风扇对PCB板进行冷却，保证焊接效果；

销售热线：186 6538 6516王振超



震讯科技

ZHENXUN TECHNOLOGY

Features:

1. With controller and button to control the machine manual. Adjust height of top heater by hand, with vacuum pen to pick BGA manual after reflow.
2. Top and bottom heater use hot air, 3rd heater use IR to preheat whole PCB board. Bottom heater can adjust up and down to support the bottom of BGA.
3. Top heater can set 8 segments heating, cooling and constant temperature, save 10 groups temperature profile. Bottom and IR heater can set 1 segment heating and constant temperature.
4. Three heater use independent PID control, heating process is more accurate and uniform.
5. Bottom heater equipped with support, can adjust up and down to support bottom side of PCB board to prevent deformation.
6. There is support on top of IR heater to prevent PCB deformation.
7. Cross-flow fan to cool PCB board after remove and reflow to ensure welding effect.

销售热线：186 6538 6516王振超

SPECIFICATION 技术规格

PCB尺寸	PCB Size	≤L540 × W 450mm
PCB厚度	PCB Thickness	0.5~3mm
温度控制	Temperature Control	K型热电偶 (K Sensor) 闭环控制 (Closed loop)
PCB定位方式	PCB Positioning	外型 (Outer)
底部预热	Sub (Bottom) heater	红外 (Infrared) 2400W
喷嘴加热	Main (Top) heater	热风 (Hot air) 800W+800W
使用电源	Power used	单相 (Single phase) 220V,50/60Hz,3.4KVA
机器尺寸	Machine dimension	L520 × W620 × H540mm
机器重量	Weight of machine	约 (Approx.) 33kgs

销售热线: 186 6538 6516王振超